

# Editorial

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Dear IMAPS Member,

Welcome to Volume 1, Number 2 of IMAPS' Journal of Microelectronics and Electronic Packaging.

First, I want to acknowledge the excellent cooperation that I have received from Prof. Jerry Sargent, PhD, in transitioning the Editorship to me. Additionally, I thank him for refereeing the first five articles in this issue.

I am pleased to announce the addition of the following to the Journal's Advisory Board: Dr. Rita Mohanty, PhD, Ark-Les Corp; Kostas Zafiriou, Polychromix Corp, Dr. Charles Barnes, PhD, JPL-CIT and Dr. Thomas Marinis, PhD, C.S.Draper Labs.

This issue covers topics from BCB to CSP, to thermal effects, to CBGA and sensors. What would we do without acronyms?!

Regards,

Delip “Doug” Bokil  
Editor-in-Chief